



401 River Oaks Parkway, San Jose, California 95134 (408) 577-6200

Green SOT363 Package Material Constituents – This Package is both RoHS-Compliant and Green

Package Element	Material Type	CAS Number	Weight (mg)
SOT363 Leadframe Bulk	Copper	7440-50-8	3.0200
SOT363 Leadframe Bulk	Iron	7439-89-6	0.0620
SOT363 Leadframe Bulk	Phosphorus	7723-14-0	0.0372
SOT363 Leadframe Bulk	Zinc	7440-66-6	0.0100
SOT363 Leadframe Terminal Finish	Matte Tin	7440-31-5	0.1808
Wirebond & Die Metallization	Gold	7440-57-5	0.0077
Die Attach Epoxy*	Silver	7440-22-4	0.0015
Die Attach Epoxy*	Epoxide Resin		0.0007
Package Molding Compound	Epoxy, Cresol Novolac	29690-82-2	0.0728
Package Molding Compound	Silica	7631-86-9	3.1950
Package Molding Compound	Epoxide Resins		0.4000
Package Molding Compound	Carbon	7440-44-0	0.0077
Active Semiconductor Die*	Arsenic	7440-38-2	0.0003
Active Semiconductor Die*	Gallium	7440-55-3	0.0026
		Total Package Weight (mg)	6.99

- Individual amounts vary slightly based on die size.

For questions, please contact Tad Custer, WJ Product Line Manager, at 408-577-6370 or Tad.Custer@wj.com.



SIZE

A

SCALE

DWG. NO.

454509

REV.

-

SHEET

2